

## DS28E22

# 1-Wire SHA-256安全认证器， 带有2Kb用户EEPROM

### 概述

DS28E22将强加密、双向、安全质询-应答安全认证功能与符合FIPS 180-3安全散列算法(SHA-256)的方案结合在一起。2Kb用户可编程EEPROM阵列为应用数据提供了非易失存储空间，具有附加保护的存储器存储SHA-256操作的密码和用户存储器控制设置。每片器件都拥有唯一的64位ROM识别码(ROM ID)，由工厂写至芯片。唯一的ROM ID用作加密运算的基本输入参数，也作为应用中的电子序列号。双向安全模型允许主机系统和嵌入式DS28E22从机之间的双向安全认证。主机系统采用从机至主机安全认证，安全验证连接或嵌入式DS28E22的合法性。主机到从机的安全认证用于保护DS28E22用户存储器不被非法主机更改。DS28E22产生的SHA-256信息验证代码(MAC)根据用户存储器中的数据、片上密码、主机随机质询及64位ROM ID计算得到。DS28E22通过单触点1-Wire®总线进行高速通信，通信符合1-Wire协议，在多器件的1-Wire网络中，ROM ID为节点地址。

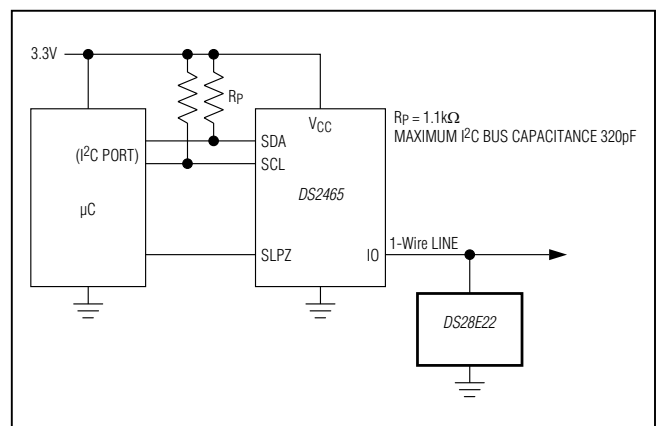
### 应用

- 联网器械的安全认证
- 打印机墨盒ID/安全认证
- 参考设计许可管理
- 系统知识产权保护
- 传感器/配件识别和校准
- 可配置系统的安全功能设置
- 加密系统的密码发生和交换

### 特性

- ◆ 基于SHA-256的对称加密双向安全认证模型
- ◆ 专用的硬件SHA加速引擎产生SHA-256 MAC
- ◆ 利用高位计数、用户可编程密码及输入质询进行有效的安全认证
- ◆ 2048位用户EEPROM存储器，分为8页，每页256位
- ◆ 用户可编程、不可擦除EEPROM保护模式，包括：安全认证、读/写保护以及OTP/EPROM仿真
- ◆ 唯一的工厂编程64位识别码
- ◆ 单触点1-Wire接口与主机通信，速度可达76.9kbps
- ◆ 工作范围：3.3V ±10%，-40°C至+85°C
- ◆ 5μA (典型值)低待机功
- ◆ ±8kV人体模式ESD保护(典型值)
- ◆ 6引脚TDFN、6引脚TSOC封装

### 典型应用电路



订购信息在数据资料的最后给出。

DeepCover是和1-Wire分别是Maxim Integrated Products, Inc.的商标和注册商标。

相关型号以及配合该器件使用的推荐产品，请参见：[china.maximintegrated.com/DS28E22.related](http://china.maximintegrated.com/DS28E22.related)。

本文是英文数据资料的译文，文中可能存在翻译上的不准确或错误。如需进一步确认，请在您的设计中参考英文资料。有关价格、供货及订购信息，请联络Maxim亚洲销售中心：10800 852 1249 (北中国区)，10800 152 1249 (南中国区)，或访问Maxim的中文网站：[china.maximintegrated.com](http://china.maximintegrated.com)。

## DS28E22

### 1-Wire SHA-256安全认证器， 带有2Kb用户EEPROM

#### ABSOLUTE MAXIMUM RATINGS

IO Voltage Range to GND..... -0.5V to 4.0V  
 IO Sink Current.....20mA  
 Operating Temperature Range..... -40°C to +85°C  
 Junction Temperature .....+150°C

Storage Temperature Range..... -55°C to +125°C  
 Lead Temperature (soldering, 10s) .....+300°C  
 Soldering Temperature (reflow) .....+260°C

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

#### ELECTRICAL CHARACTERISTICS

(T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>IO PIN: GENERAL DATA</b>						
1-Wire Pullup Voltage	V <sub>PUP</sub>	(Note 2)	2.97		3.63	V
1-Wire Pullup Resistance	R <sub>PUP</sub>	V <sub>PUP</sub> = 3.3V ± 10% (Note 3)	300		1500	Ω
Input Capacitance	C <sub>IO</sub>	(Notes 4, 5)		1500		pF
Input Load Current	I <sub>L</sub>	IO pin at V <sub>PUP</sub>		5	19.5	μA
High-to-Low Switching Threshold	V <sub>TL</sub>	(Notes 6, 7)		0.65 x V <sub>PUP</sub>		V
Input Low Voltage	V <sub>IL</sub>	(Notes 2, 8)			0.3	V
Low-to-High Switching Threshold	V <sub>TH</sub>	(Notes 6, 9)		0.75 x V <sub>PUP</sub>		V
Switching Hysteresis	V <sub>HY</sub>	(Notes 6, 10)		0.3		V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 4mA (Note 11)			0.4	V
Recovery Time	t <sub>REC</sub>	R <sub>PUP</sub> = 1500Ω (Notes 2, 12)	5			μs
Time-Slot Duration	t <sub>SLOT</sub>	(Notes 2, 13)	13			μs
<b>IO PIN: 1-Wire RESET, PRESENCE-DETECT CYCLE</b>						
Reset Low Time	t <sub>RSTL</sub>	(Note 2)	48		80	μs
Reset High Time	t <sub>RSTH</sub>	(Note 14)	48			μs
Presence-Detect Sample Time	t <sub>MSP</sub>	(Notes 2, 15)	8		10	μs
<b>IO PIN: 1-Wire WRITE</b>						
Write-Zero Low Time	t <sub>W0L</sub>	(Notes 2, 16)	8		16	μs
Write-One Low Time	t <sub>W1L</sub>	(Notes 2, 16)	1		2	μs
<b>IO PIN: 1-Wire READ</b>						
Read Low Time	t <sub>RL</sub>	(Notes 2, 17)	1		2 - δ	μs
Read Sample Time	t <sub>MSR</sub>	(Notes 2, 17)	t <sub>RL</sub> + δ		2	μs
<b>EEPROM</b>						
Programming Current	I <sub>PROG</sub>	V <sub>PUP</sub> = 3.63V (Notes 5, 18)			1	mA
Programming Time for a 32-Bit Segment or Page Protection	t <sub>PRD</sub>	<b>Refer to the full data sheet.</b>				ms
Programming Time for the Secret	t <sub>PRS</sub>					ms
Write/Erase Cycling Endurance	N <sub>CY</sub>	T <sub>A</sub> = +85°C (Notes 21, 22)	100k			—
Data Retention	t <sub>DR</sub>	T <sub>A</sub> = +85°C (Notes 23, 24, 25)	10			Years

## DS28E22

### 1-Wire SHA-256安全认证器， 带有2Kb用户EEPROM

#### ELECTRICAL CHARACTERISTICS (continued)

( $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ , unless otherwise noted.) (Note 1)

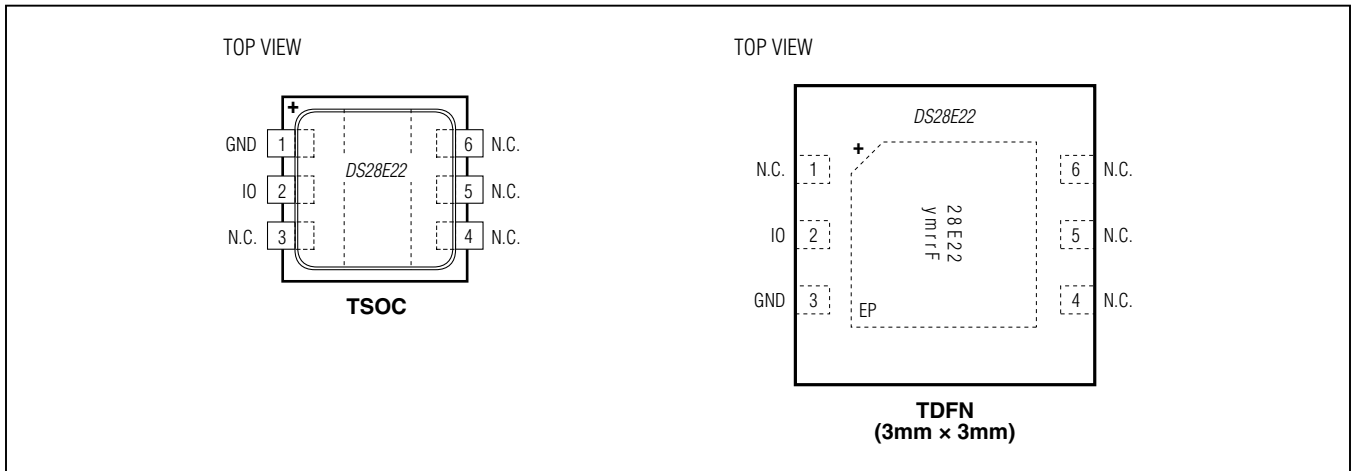
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>SHA-256 ENGINE</b>						
Computation Current	$I_{\text{CSHA}}$	Refer to the full data sheet.				mA
Computation Time	$t_{\text{CSHA}}$					ms

- Note 1:** Limits are 100% production tested at  $T_A = +25^{\circ}\text{C}$  and/or  $T_A = +85^{\circ}\text{C}$ . Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization. Typical values are not guaranteed.
- Note 2:** System requirement.
- Note 3:** Maximum allowable pullup resistance is a function of the number of 1-Wire devices in the system and 1-Wire recovery times. The specified value here applies to systems with only one device and with the minimum 1-Wire recovery times.
- Note 4:** Typical value represents the internal parasite capacitance when  $V_{\text{PUP}}$  is first applied. Once the parasite capacitance is charged, it does not affect normal communication.
- Note 5:** Guaranteed by design and/or characterization only; not production tested.
- Note 6:**  $V_{\text{TL}}$ ,  $V_{\text{TH}}$ , and  $V_{\text{HY}}$  are a function of the internal supply voltage, which is a function of  $V_{\text{PUP}}$ ,  $R_{\text{PUP}}$ , 1-Wire timing, and capacitive loading on IO. Lower  $V_{\text{PUP}}$ , higher  $R_{\text{PUP}}$ , shorter  $t_{\text{REC}}$ , and heavier capacitive loading all lead to lower values of  $V_{\text{TL}}$ ,  $V_{\text{TH}}$ , and  $V_{\text{HY}}$ .
- Note 7:** Voltage below which, during a falling edge on IO, a logic-zero is detected.
- Note 8:** The voltage on IO must be less than or equal to  $V_{\text{ILMAX}}$  at all times when the master is driving IO to a logic-zero level.
- Note 9:** Voltage above which, during a rising edge on IO, a logic-one is detected.
- Note 10:** After  $V_{\text{TH}}$  is crossed during a rising edge on IO, the voltage on IO must drop by at least  $V_{\text{HY}}$  to be detected as logic-zero.
- Note 11:** The I-V characteristic is linear for voltages less than 1V.
- Note 12:** Applies to a single device attached to a 1-Wire line.
- Note 13:** Defines maximum possible bit rate. Equal to  $1/(t_{\text{WOLMIN}} + t_{\text{RECMIN}})$ .
- Note 14:** An additional reset or communication sequence cannot begin until the reset high time has expired.
- Note 15:** Interval after  $t_{\text{RSTL}}$  during which a bus master can read a logic 0 on IO if there is a DS28E22 present. The power-up presence detect pulse could be outside this interval, but will be complete within 2ms after power-up.
- Note 16:**  $\epsilon$  in [Figure 11](#) represents the time required for the pullup circuitry to pull the voltage on IO up from  $V_{\text{IL}}$  to  $V_{\text{TH}}$ . The actual maximum duration for the master to pull the line low is  $t_{\text{W1LMAX}} + t_{\text{F}} - \epsilon$  and  $t_{\text{W0LMAX}} + t_{\text{F}} - \epsilon$ , respectively.
- Note 17:**  $\delta$  in [Figure 11](#) represents the time required for the pullup circuitry to pull the voltage on IO up from  $V_{\text{IL}}$  to the input-high threshold of the bus master. The actual maximum duration for the master to pull the line low is  $t_{\text{RLMAX}} + t_{\text{F}}$ .
- Note 18:** Current drawn from IO during the EEPROM programming interval or SHA-256 computation. The pullup circuit on IO during the programming interval or SHA-256 computation should be such that the voltage at IO is greater than or equal to 2.0V.
- Note 19: Refer to the full data sheet.**
- Note 20: Refer to the full data sheet.**
- Note 21:** Write-cycle endurance is tested in compliance with JESD47G.
- Note 22:** Not 100% production tested; guaranteed by reliability monitor sampling.
- Note 23:** Data retention is tested in compliance with JESD47G.
- Note 24:** Guaranteed by 100% production test at elevated temperature for a shorter time; equivalence of this production test to the data sheet limit at operating temperature range is established by reliability testing.
- Note 25:** EEPROM writes can become nonfunctional after the data retention time is exceeded. Long-term storage at elevated temperatures is not recommended.
- Note 26: Refer to the full data sheet.**

## DS28E22

### 1-Wire SHA-256安全认证器， 带有2Kb用户EEPROM

#### 引脚配置



#### 引脚说明

引脚		名称	功能
TSOC	TDFN-EP		
1	3	GND	地基准。
2	2	IO	1-Wire总线接口。开漏信号，需要外部上拉电阻。
3, 4, 5, 6	1, 4, 5, 6	N.C.	无连接。
—	—	EP	裸焊盘(仅限TDFN封装)。均匀焊接至电路板的接地区域以确保正常工作。更多信息请参见应用笔记3273: <i>Exposed Pads: A Brief Introduction</i> 。

## DS28E22

### 1-Wire SHA-256安全认证器， 带有2Kb用户EEPROM

**注意：**该文件是完整数据资料的缩略版。其他产品信息仅在完整版的数据资料中。如需申请完整版，请浏览[china.maximintegrated.com/DS28E22](http://china.maximintegrated.com/DS28E22)并点击**申请数据资料全文**。

#### 订购信息

器件	温度范围	引脚-封装
DS28E22P+	-40°C至+85°C	6 TSOC
DS28E22P+T	-40°C至+85°C	6 TSOC (4k pcs)
DS28E22Q+T	-40°C至+85°C	6 TDFN-EP* (2.5k pcs)

+表示无铅(Pb)/符合RoHS标准的封装。

T = 卷带包装。

\*未来产品—供货状况请联系工厂。

\*EP = 裸焊盘。

#### 封装信息

如需最近的封装外形信息和焊盘布局(占位面积)，请查询[china.maximintegrated.com/packages](http://china.maximintegrated.com/packages)。请注意，封装编码中的“+”、“#”或“-”仅表示RoHS状态。封装图中可能包含不同的尾缀字符，但封装图只与封装有关，与RoHS状态无关。

封装类型	封装编码	外形编号	焊盘布局编号
6 TSOC	D6+1	<a href="#">21-0382</a>	<a href="#">90-0321</a>
6 TDFN-EP	T633+2	<a href="#">21-0137</a>	<a href="#">90-0058</a>

## Maxim北京办事处

北京8328信箱 邮政编码100083

免费电话：800 810 0310

电话：010-6211 5199

传真：010-6211 5299



Maxim不对Maxim产品以外的任何电路使用负责，也不提供其专利许可。Maxim保留在任何时间、没有任何通报的前提下修改产品资料和规格的权利。电气特性表中列出的参数值(最小值和最大值)均经过设计验证，数据资料其它章节引用的参数值供设计人员参考。

**Maxim Integrated 160 Rio Robles, San Jose, CA 95134 USA 1-408-601-10 00**

5